



IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Osamu NAKAGAWA et al.

Confirmation No.: 3635

Application No.: 09/891,324

Examiner: L. SCHILLINGER

Filing Date: June 27, 2001

Group Art Unit: 2813

Title: PROCESS FOR HIGH-DIELECTRIC CONSTANT METAL-INSULATOR METAL CAPACITOR
IN VLSI MULTI-LEVEL METALLIZATION SYSTEMS

COMMISSIONER FOR PATENTS
Washington, D.C. 20231

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TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

GROUP 3600

Sir:

Transmitted herewith is/are the following in the above-identified application:

- (X) Response/Amendment () Petition to extend time to respond
() New fee as calculated below () Supplemental Declaration
(X) No additional fee (Address envelope to "Box Non-Fee Amendments")
() Other: (fee \$)

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	13	MINUS	20	= 0	X \$18	\$ 0
INDEP. CLAIMS	1	MINUS	3	= 0	X \$84	\$ 0
[] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ \$280	\$ 0
EXTENSION FEE	1ST MONTH \$110.00	2ND MONTH \$400.00	3RD MONTH \$920.00	4TH MONTH \$1440.00		\$ 0
OTHER FEES						\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 0

Charge \$ 0 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16 through 1.21 inclusive, and any other sections in Title 37 of the Code of Federal Regulations that may regulate fees. A duplicate copy of this sheet is enclosed.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit:

Typed Name:

Signature: _____

Respectfully submitted,

Osamu NAKAGAWA et al.

By

John W. Ryan

JOHN W. RYAN

Attorney/Agent for Applicant(s)

Reg. No. 33,771

Date: January 4, 2003

HEWLETT-PACKARD COMPANY
Intellectual Property Administration
P.O. Box 272400
Fort Collins, Colorado 80527-2400

PATENT
Docket No. 10004808-1

#5/
Response
1-17-03
L. Spruell



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor O. NAKAGAWA et al. Examiner: L. Schillinger
Application No.: 09/891,324 Confirmation No.: 3635
Filed: June 27, 2001 Group Art Unit: 2813
Title: *PROCESS FOR HIGH-DIELECTRIC CONSTANT METAL-INSULATOR METAL
CAPACITOR IN VLSI MULTI-LEVEL METALLIZATION SYSTEMS*

RESPONSE UNDER 37 C.F.R. §1.111

BOX NO-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

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GROUP 3600

Sir:

In response to the Office Action mailed October 7, 2002, the Applicants respectfully request the Examiner to consider the following remarks:

REMARKS

Claims 14-19 have been withdrawn from consideration. Thus, claims 1-13 are pending.

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TECHNOLOGY CENTER
2800

35 U.S.C. § 102(b) REJECTION OF CLAIMS 1-4 and 7-13

In the Office Action, claims 1-4 and 7-13 were rejected under 35 U.S.C. § 102(b) as allegedly being anticipated by Lou U.S. Pat. No. 6,162,680 (Lou). The Applicants respectfully traverse the rejection.

Claims 1-4 and 7-13 recite, *inter alia*, a method of forming a bypass capacitor that includes forming a first electrode in a first metal layer.